

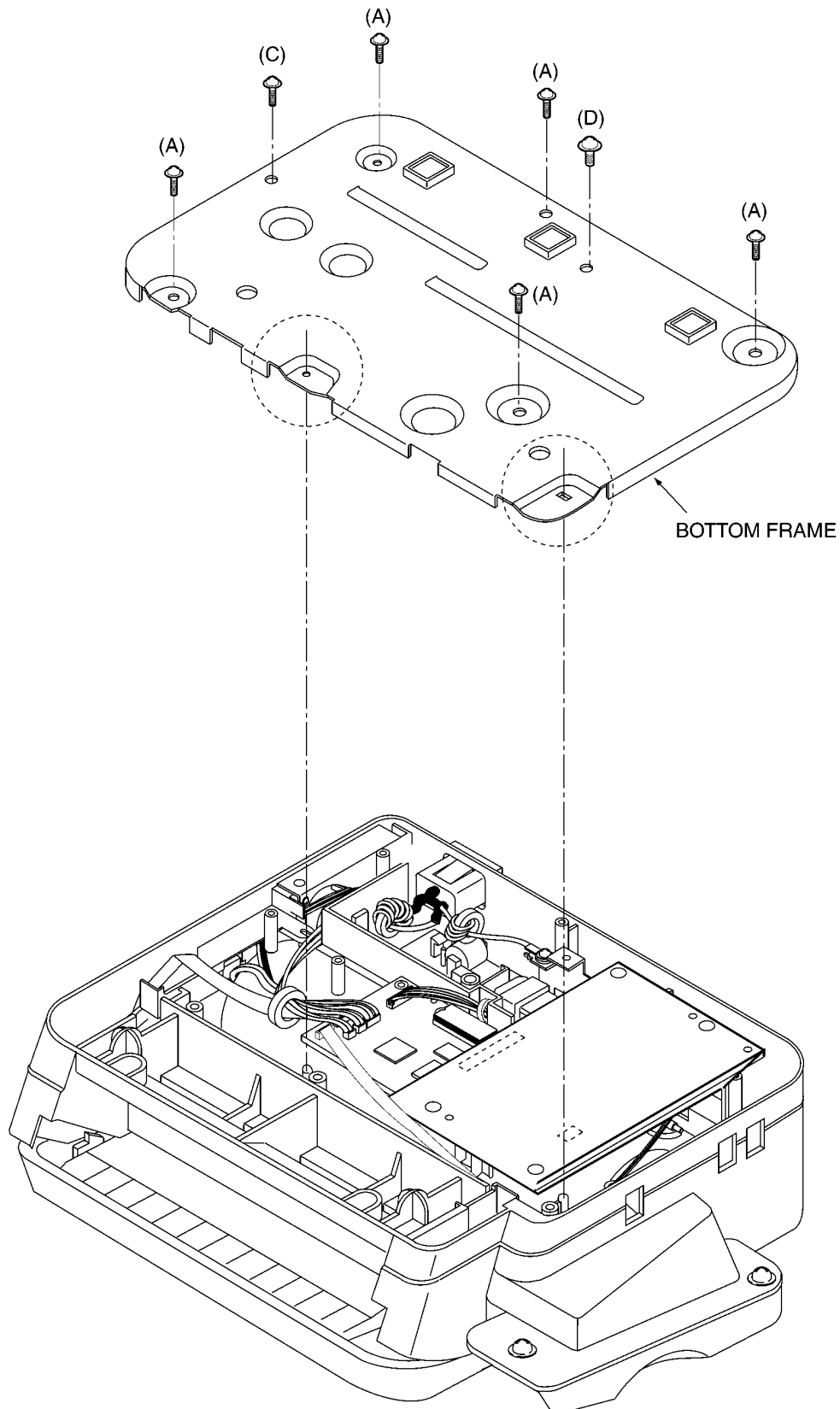
3 DISASSEMBLY INSTRUCTIONS

3.1. HOW TO REMOVE THE BOTTOM FRAME

Procedure 1

Ref. No. 1

- 1) Remove the 7 screws (A),(C),(D).
- 2) Remove the Bottom frame.

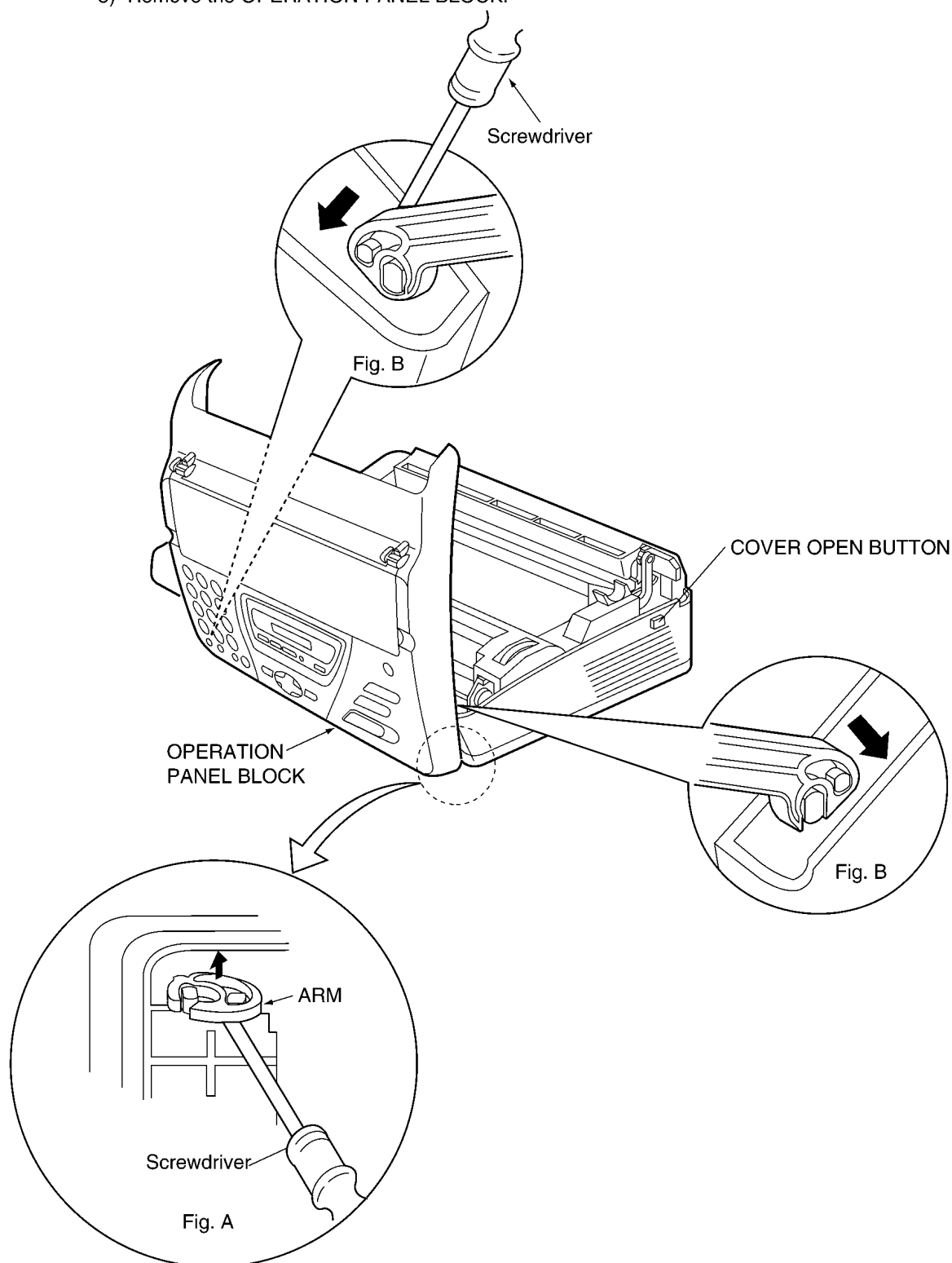


3.2. HOW TO REMOVE THE OPERATION PANEL BLOCK

Procedure 2

Ref. No. 2

- 1) Unhook all the connectors connecting the main cabinet with the OPERATION PANEL BLOCK .
- 2) Push the cover open button in the direction of the arrow to open the operation block.
- 3) Tilt the unit vertically so that its left side faces down the grey-shaded ARM as illustrated in Fig. A, insert a screwdriver and unlatch the ARM as illustrated in Fig. A.
- 4) Pull out both sides of the arms (in the direction of the arrow shown in Fig. B).
- 5) Remove the OPERATION PANEL BLOCK.

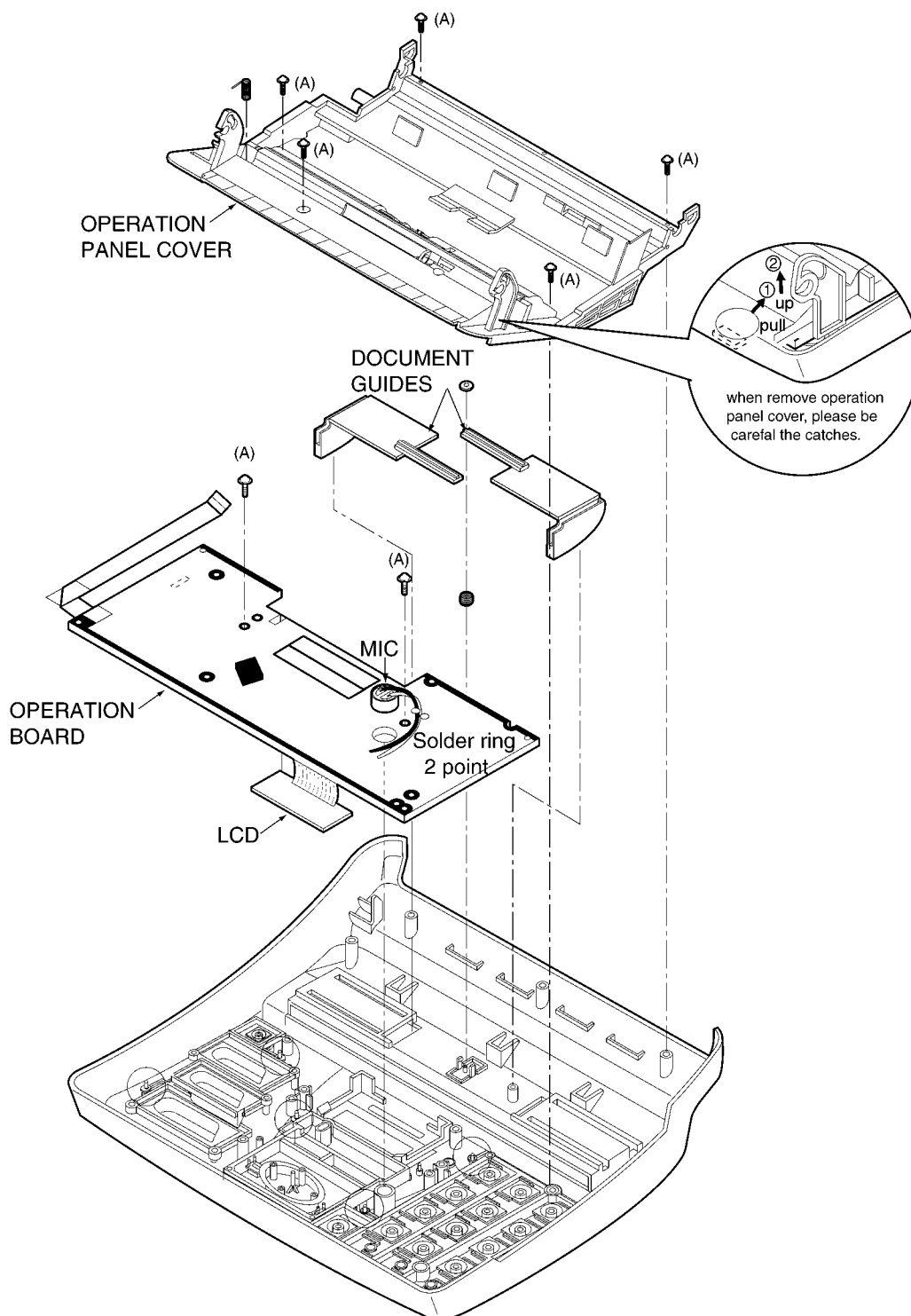


3.3. HOW TO REMOVE THE OPERATION BOARD AND LCD

Procedure 2 → 3

Ref. No. 3

- 1) Remove the 5 screws (A) of the operation panel cover.
- 2) Remove the 2 screws (A) of the operation Board.
- 3) Remove the mic.
- 4) Remove the operation board.
- 5) Remove the document guides.

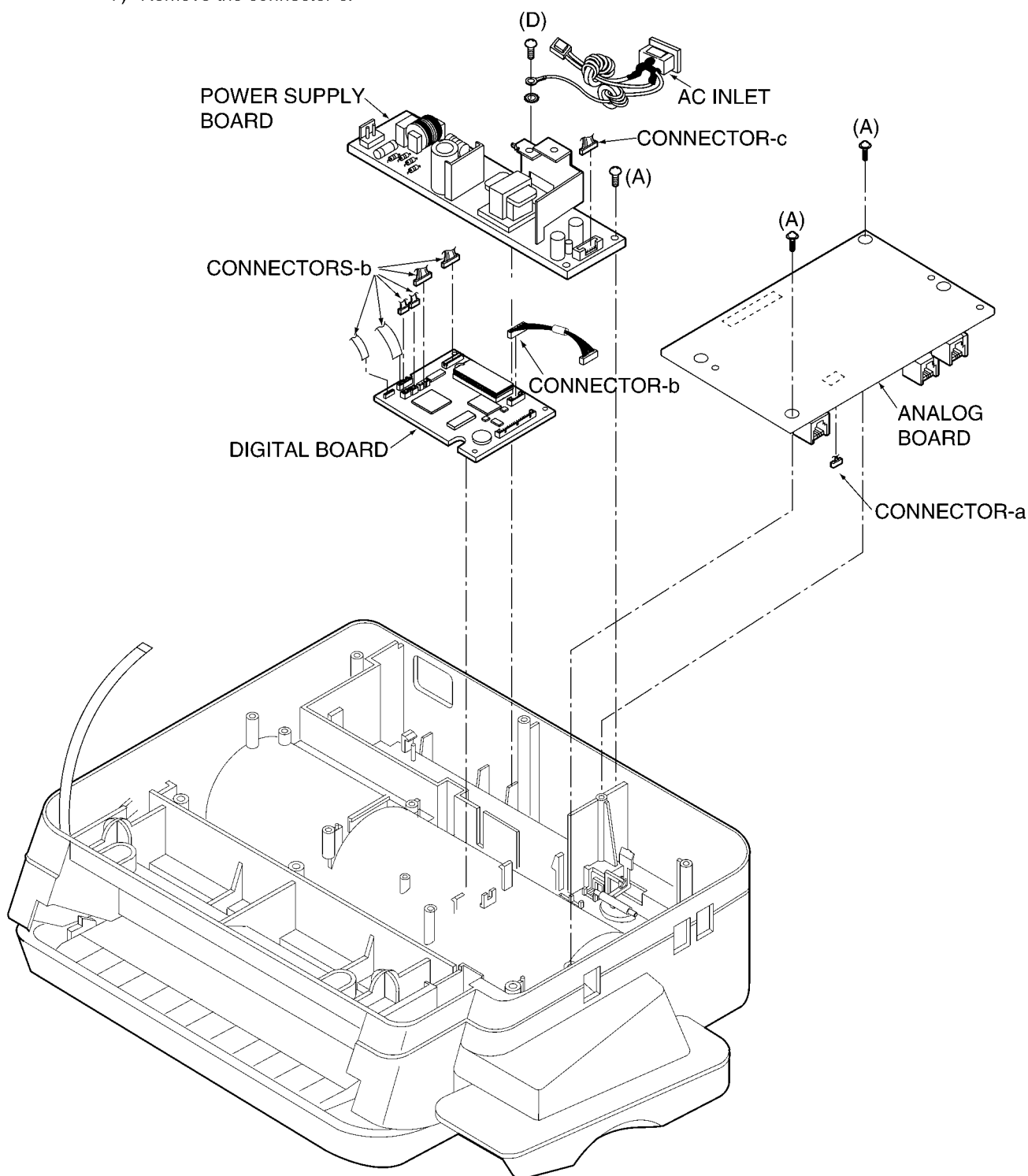


3.4. HOW TO REMOVE THE DIGITAL, ANALOG AND POWER SUPPLY BOARD AND AC INLET

Procedure 1 → 4

Ref. No. 4

- 1) Remove the 2 screws (A).
- 2) Remove the connector-a.
- 3) Remove the ANALOG BOARD.
- 4) Remove the connectors-b.
- 5) Remove the DIGITAL BOARD.
- 6) Remove the 2 screws (A),(D).
- 7) Remove the connector-c.
- 8) Remove the POWER SUPPLY BOARD.
- 9) Remove the AC INLET.



3.5. HOW TO REMOVE THE HANDSET CRADLE CABINET AND SPEAKER

Procedure 1→5

Ref. No. 5

- 1) Remove the 3 screws (A).
- 2) Push the cover open button.
- 3) Remove the HANDSET CRADLE CABINET.(see Fig.A).
- 4) Remove the SPEAKER.

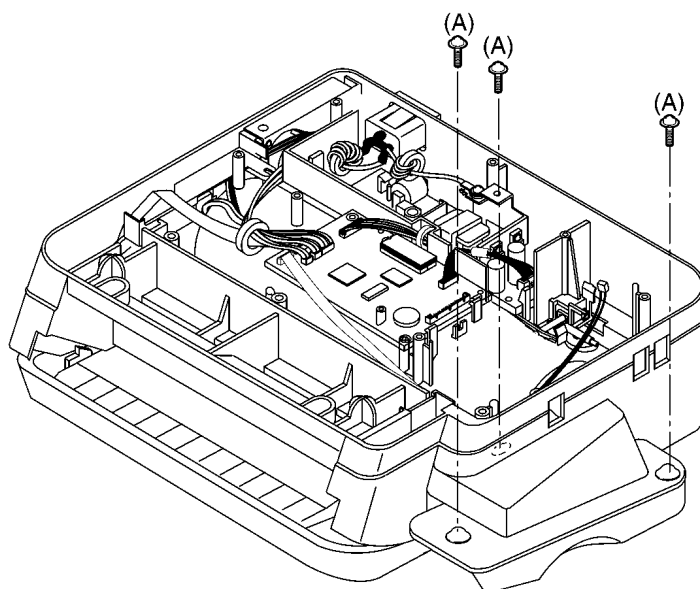
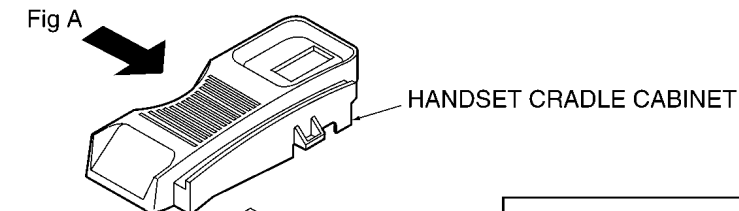
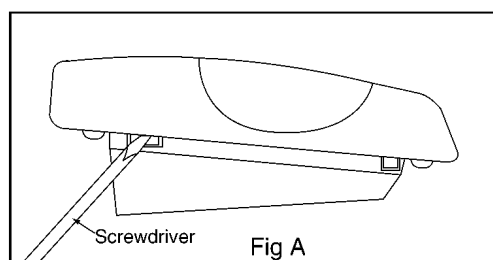


Fig A



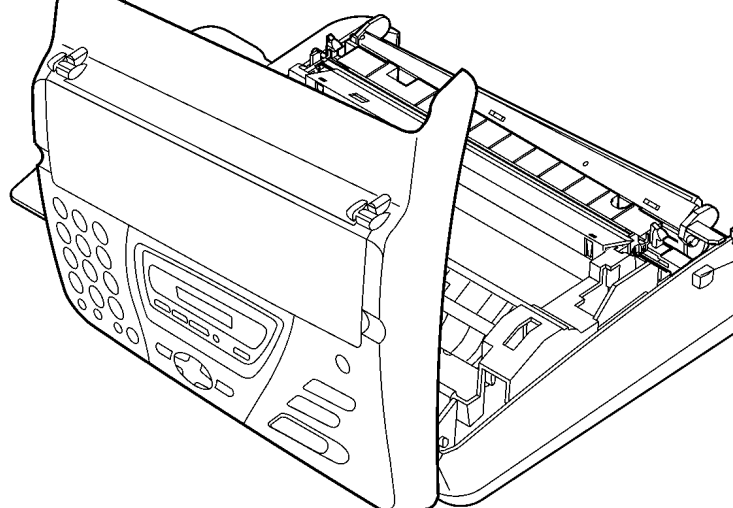
SPEAKER

HANDSET CRADLE CABINET



Screwdriver

Fig A



COVER OPEN BUTTON

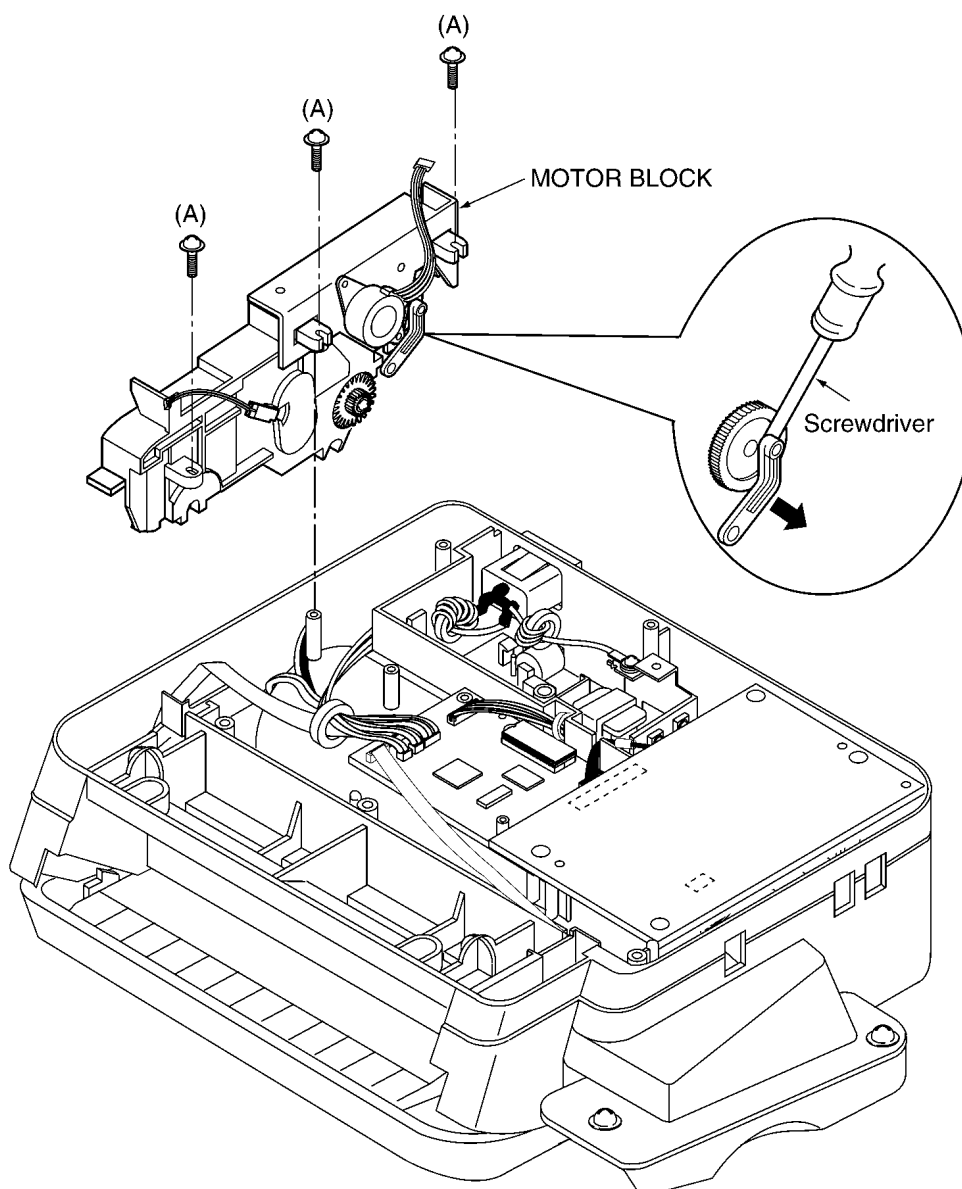
3.6. HOW TO REMOVE THE MOTOR BLOCK

Procedure 1→ 6

Ref. No. 6

- 1) Remove the 3 screw (A).
- 2) Remove the MOTOR BLOCK.

Note: When install the Motor Block into the unit, Please refer to **HOW TO REMOVE THE THERMAL HEAD AND CUTTER BLOCK.**

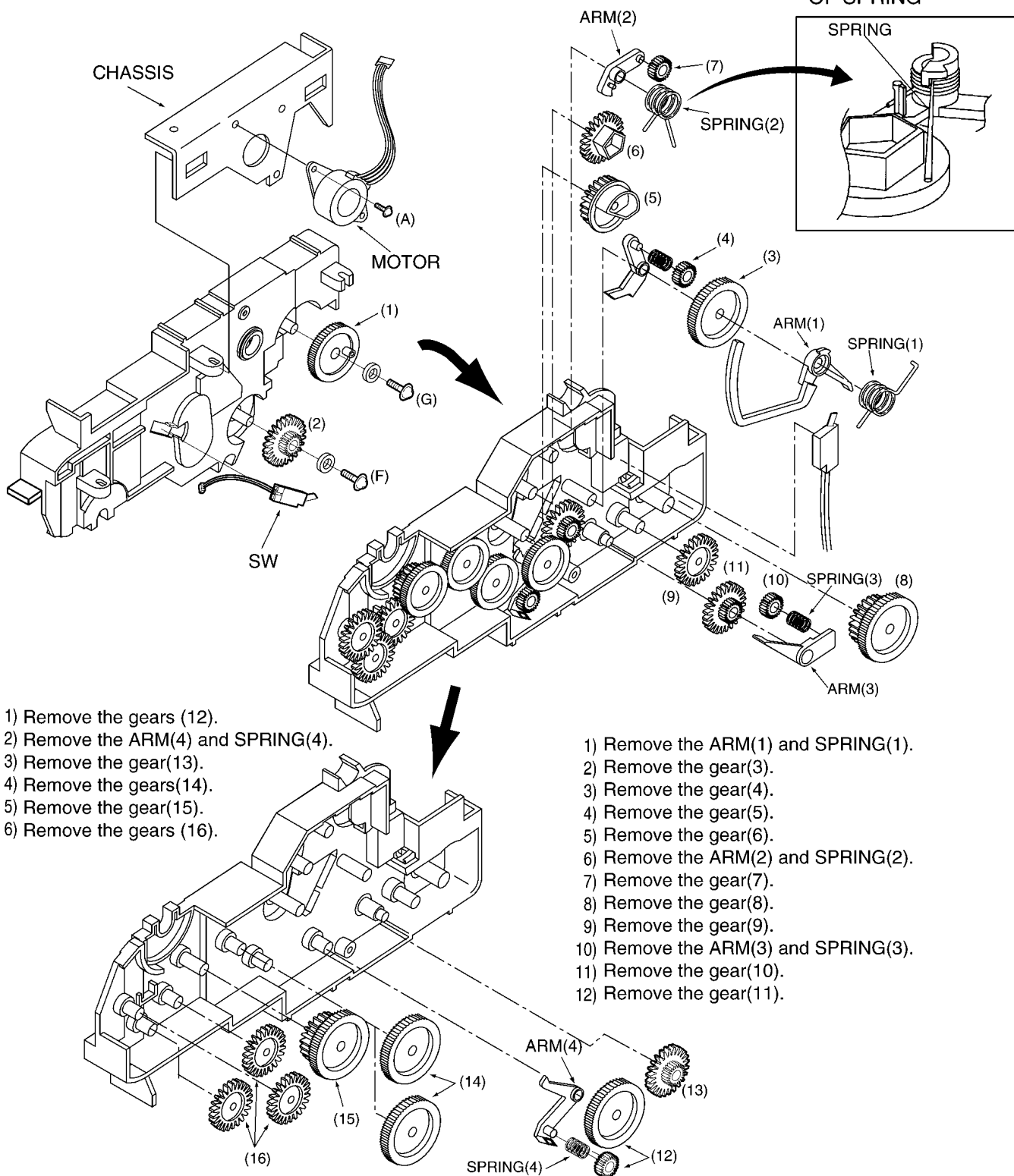


CROSS REFERENCE:**HOW TO REMOVE THE THERMAL HEAD AND CUTTER UNIT (P.104)**

Procedure 1 → 6 → 6(a)

Ref. No. 6 (a)

- 1) Remove the screw (A).
- 2) Remove the MOTOR and CHASSIS.
- 3) Remove the SW.
- 4) Remove the screw (G).
- 5) Remove the gear (1).
- 6) Remove the screw (F)
- 7) Remove the gear (2).

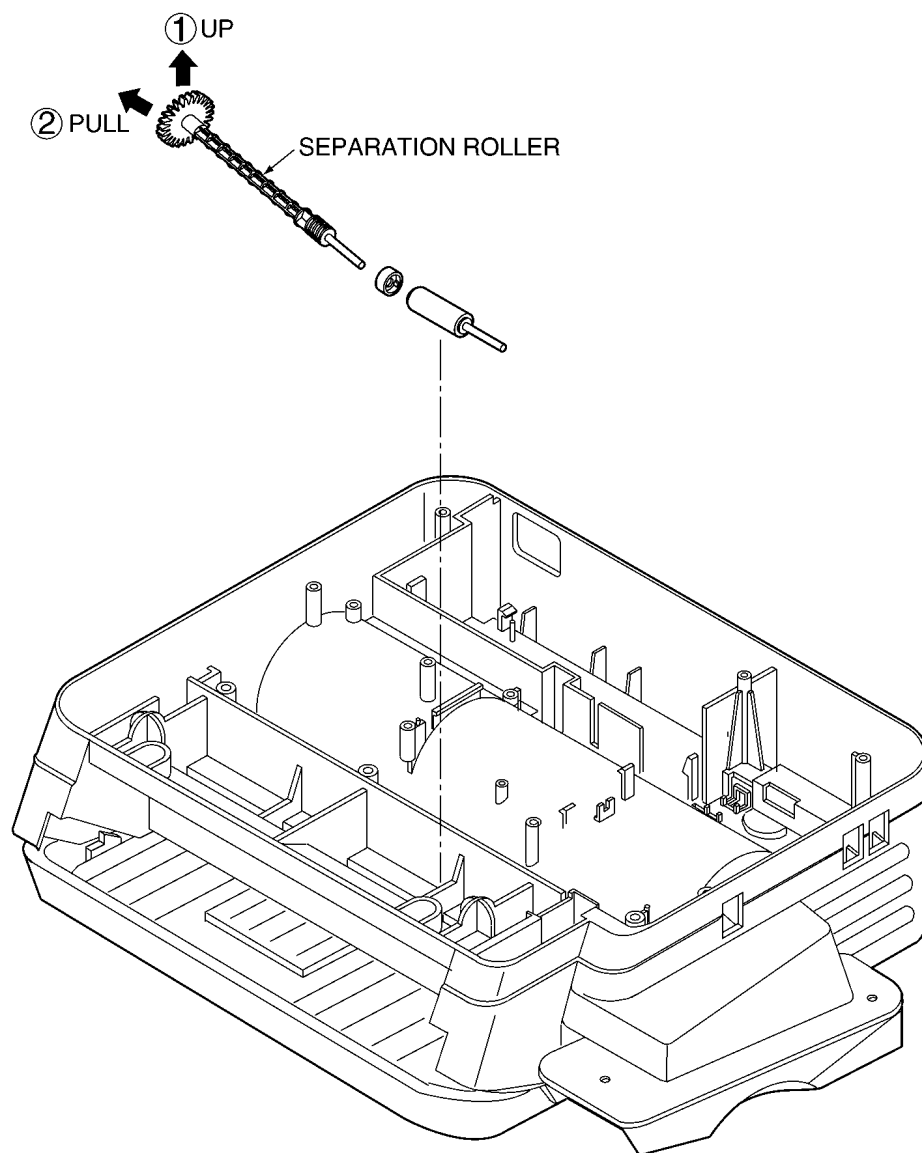


3.7. HOW TO REMOVE THE ROLLERS

Procedure 1 → 4 → 6 → 7

Ref. No. 7

1) Remove the SEPARATION ROLLER.

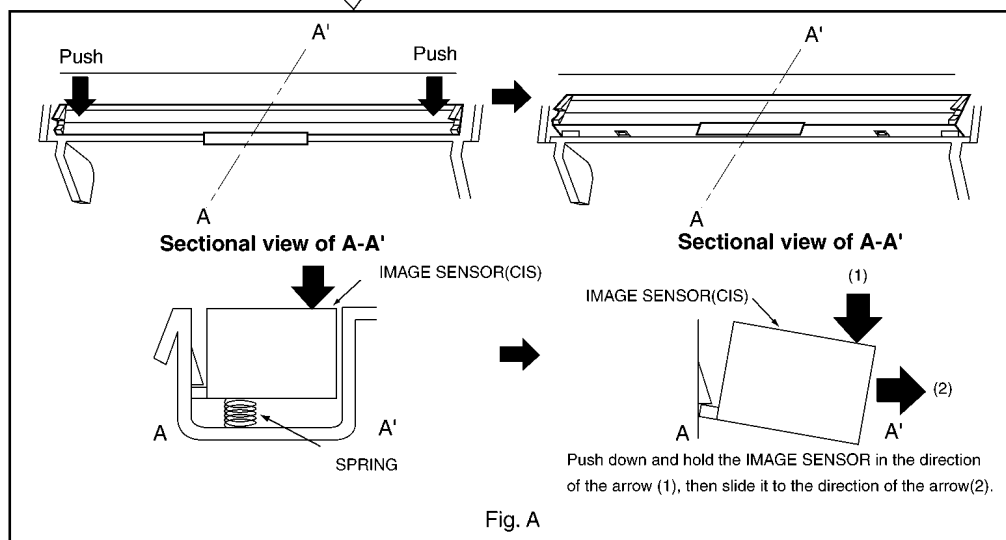
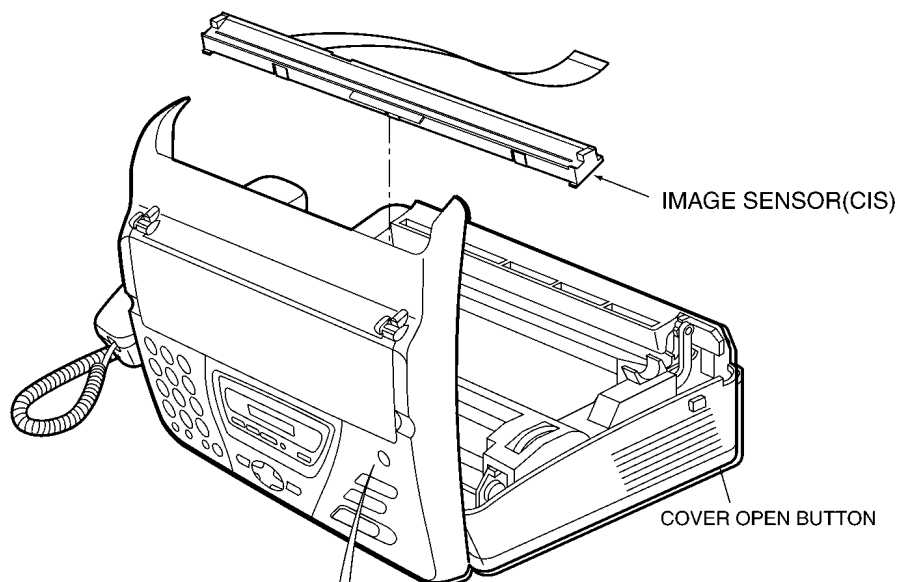


3.8. HOW TO REMOVE THE IMAGE SENSOR

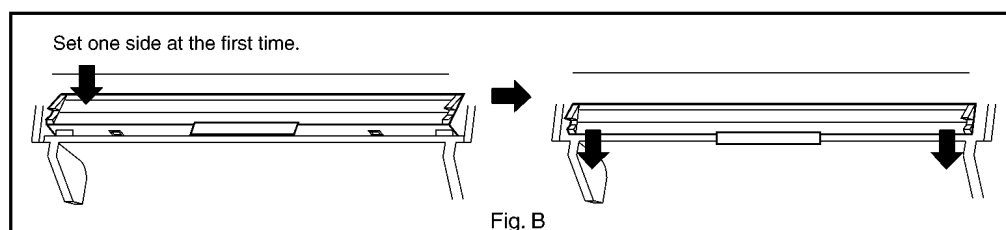
Procedure 1 → 4 → 8

Ref. No. 8

- 1) Push the cover open button.
- 2) Remove the image sensor (Refer to Fig.A.)



HOW TO INSTALL THE IMAGE SENSOR

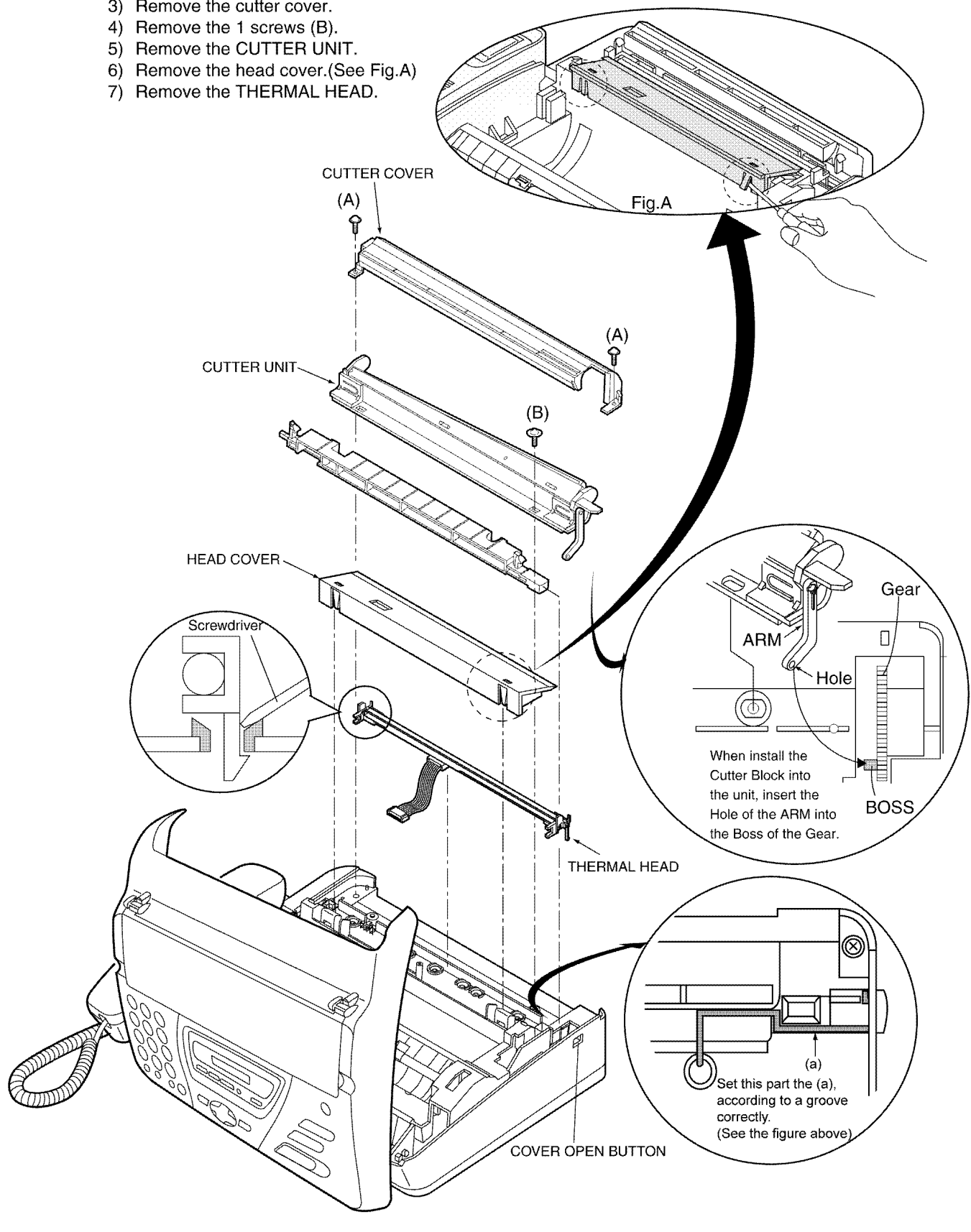


3.9. HOW TO REMOVE THE THERMAL HEAD AND CUTTER UNIT

Procedure 9

Ref. No. 9

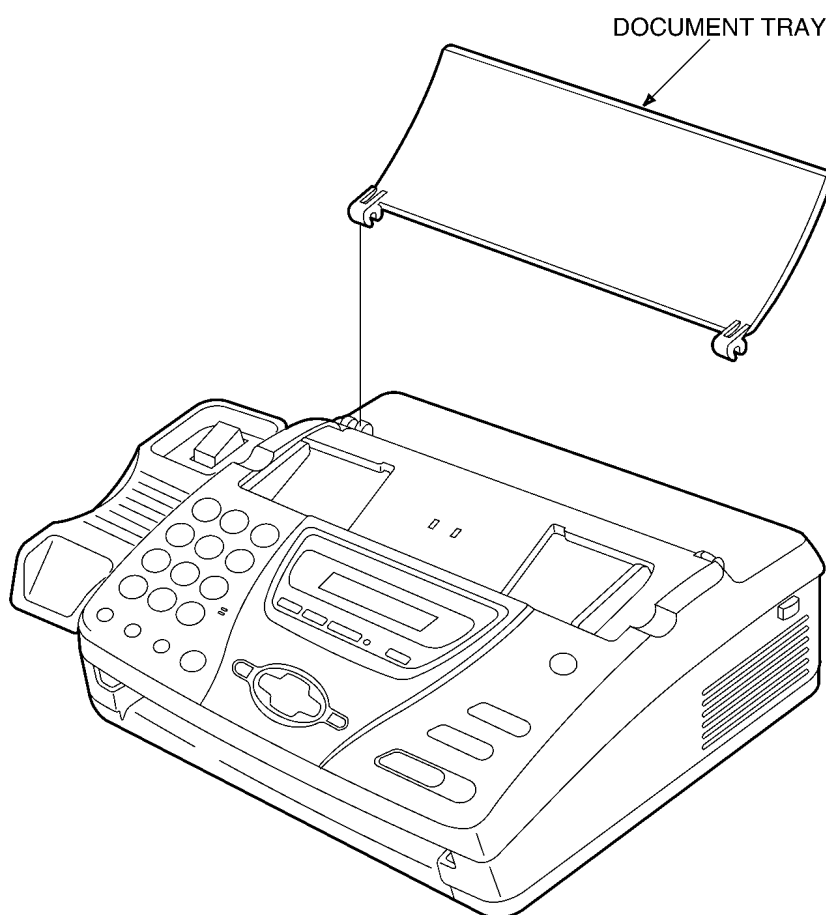
- 1) Push the cover open button.
- 2) Remove the 2 screws (A).
- 3) Remove the cutter cover.
- 4) Remove the 1 screws (B).
- 5) Remove the CUTTER UNIT.
- 6) Remove the head cover.(See Fig.A)
- 7) Remove the THERMAL HEAD.



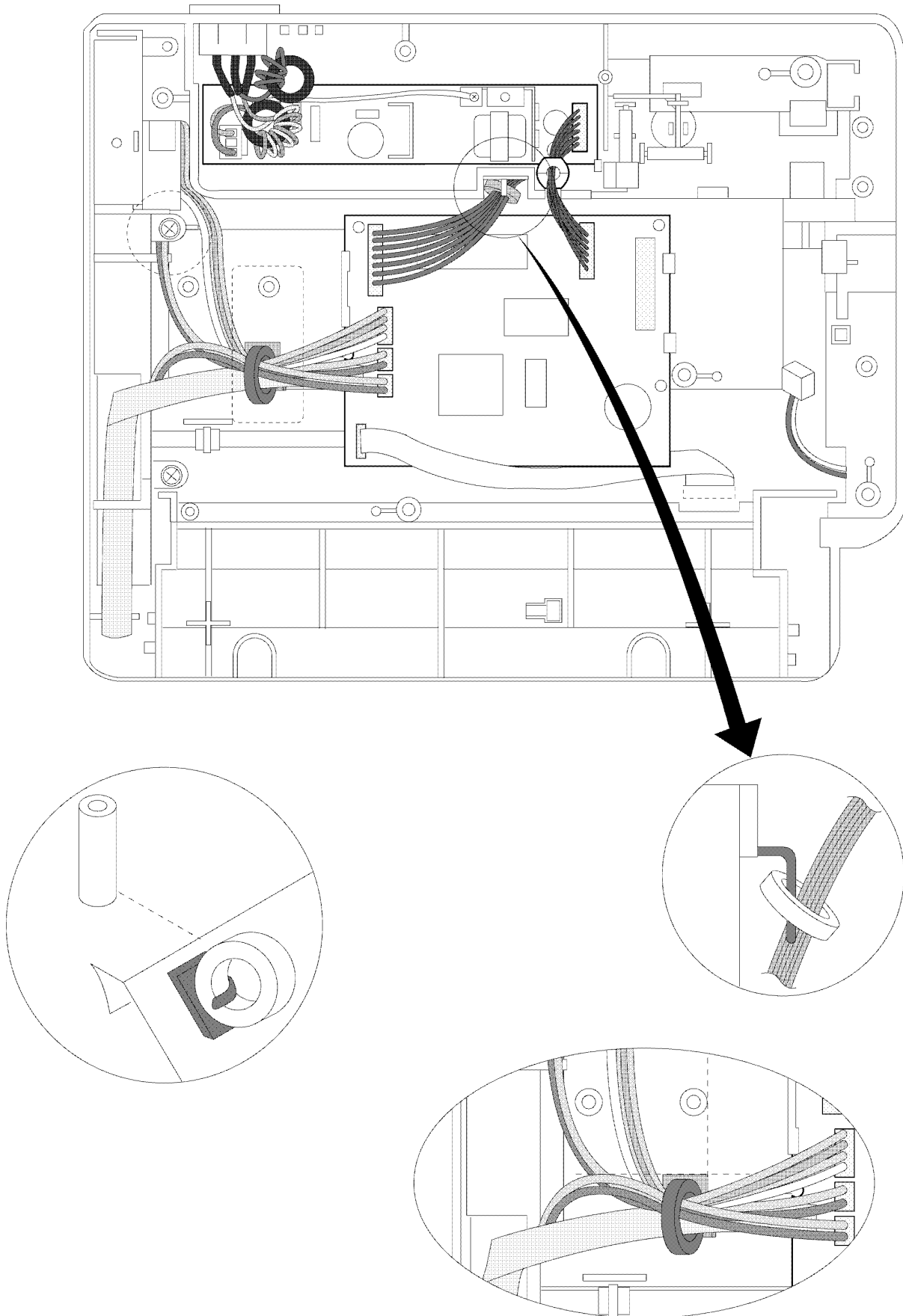
3.10. HOW TO REMOVE THE DOCUMENT TRAY

Procedure 10

Ref. No. 10 1) Remove the DOCUMENT TRAY.

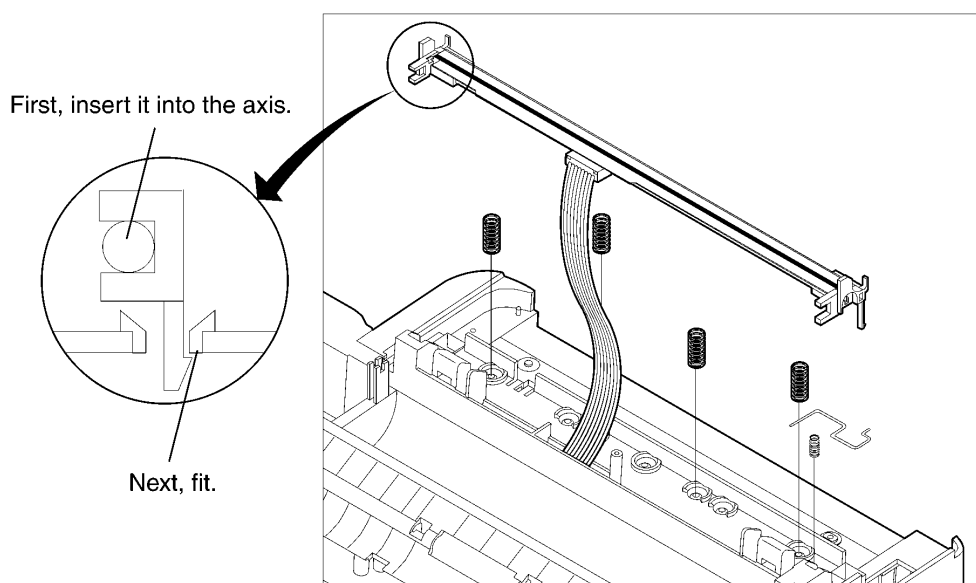


3.11. INSTALLATION POSITION OF THE LEAD WIRES



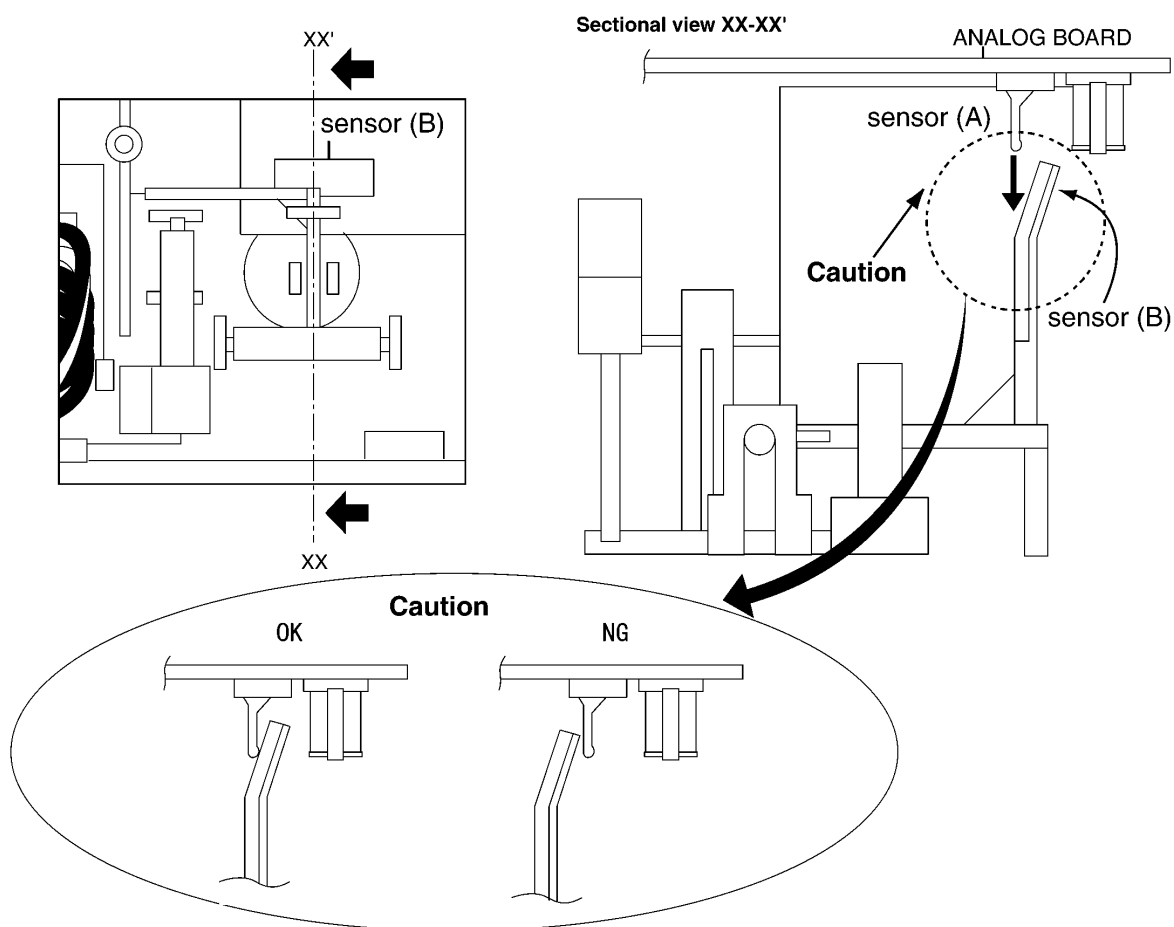
3.12. INSTALLATION OF THERMAL HEAD AND ANALOG BOARD

INSTALLATION OF THERMAL HEAD



INSTALLATION OF ANALOG BOARD

Before installing the ANALOG BOARD, make sure that the thermal paper is removed completely. When installing the ANALOG BOARD, make sure that the sensor lever(B) is set in the position of the bellow figure.



4 HOW TO REPLACE THE FLAT PACKAGE IC

If you do not have the special tools (for example: SPOT HEATER) to remove the SPOT HEATER'S Flat IC, if you have solder (large amount), a soldering iron, and a cutter knife, you can easily remove the ICs even if there are more than 100 pins.

4.1. PREPARATION

- SOLDER

Sparkle Solder 115A-1, 115B-1 OR Almit Solder KR-19, KR-19RMA

- Soldering iron

Recommended power consumption is between 30 W to 40 W.

Temperature of Copper Rod $662 \pm 50^{\circ}\text{F}$ ($350 \pm 10^{\circ}\text{C}$)

(An expert may handle a 60~80 W iron, but a beginner might damage the foil by overheating.)

- Flux

HI115 Specific gravity 0.863

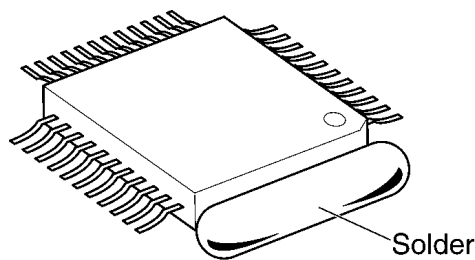
(Original flux should be replaced daily.)

4.2. FLAT PACKAGE IC REMOVAL PROCEDURE

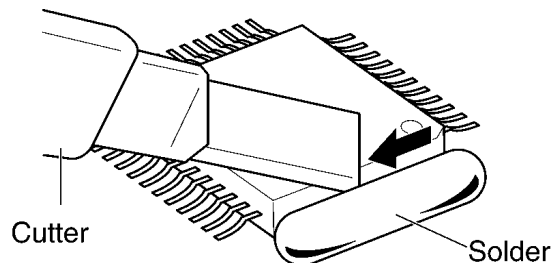
1. When all of the IC lead cannot be seen at the standard degree, fill with large quantities of solder.

Note:

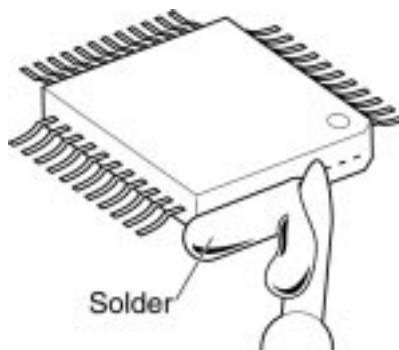
If you do not fill with solder and directly cut the IC lead with the cutter, stress may build up directly in the P.C. board's pattern. If you do not fill with large quantities of solder as in step 1, the P.C. board pattern may be removed.



2. Using a cutter, cut the lead at the source. (Cut the contents with a cutter lightly, 5 or 6 times.)



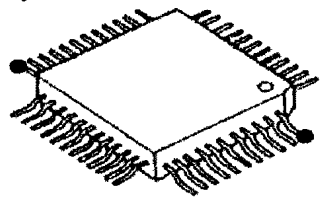
3. Remove when the solder melts. (Remove the lead at the same time.)



After removing the Flat IC and when attaching a new IC, remove any of the excess solder on the land using the soldering wire, etc. If the excess solder is not removed from the land, the IC will slip and not be attached properly

4.3. FLAT PACKAGE IC INSTALLATION PROCEDURE

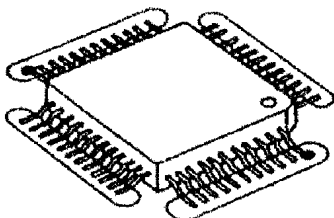
- 1) Temporarily fix the FLAT PACKAGE IC by soldering on the two marked pins.



● ————— Temporary soldering point.

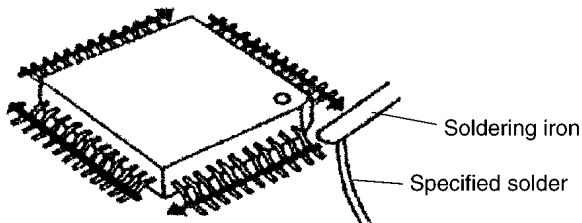
*Check the accuracy of the IC setting with the corresponding soldering foil.

- 2) Apply flux to all pins of the FLAT PACKAGE IC.



————— Flux

- 3) Solder using the specified solder, in the direction of the arrow, by sliding the soldering iron.



4.4. BRIDGE MODIFICATION PROCEDURE

- 1) Lightly re-solder the bridged portion.
- 2) Remove the remaining solder along the pins using a soldering iron as shown in the figure below.

